# LED Driver, Series Boost, with Integrated Schottky Diode and Single-Wire Digital Interface

# **FAN5341**

#### Description

The FAN5341 is an asynchronous constant-current LED driver capable of efficiently delivering up to 500 mW to a string of up to five LEDs in series. Optimized for small form-factor applications, the 1.2 MHz fixed switching frequency allows the use of small chip inductors and capacitors.

The FAN5341 uses a simple single-wire digital control interface to program the brightness levels of the LEDs in 32 linear steps by applying digital pulses.

For safety, the device features integrated over-voltage, over-current, short-circuit detection, and thermal-shutdown protection. In addition, input under-voltage lockout protection is triggered if the battery voltage is too low.

The FAN5341 is available in a very low profile, small form-factor 2 mm x 2 mm x 0.55 mm 6-lead UMLP package that is green and RoHS compliant.

#### **Features**

- Asynchronous Boost Converter
- Internal Schottky Diode
- Up to 500 mW Output Power
- Drives 3 to 5 LEDs in Series
- 2.7 V to 5.5 V Input Voltage Range
- Single-Wire Digital Control Interface to Set LED Brightness Levels
- 32 Linear Steps
- 1.2 MHz Fixed Switching Frequency
- Soft-Start Capability
- Input Under-Voltage Lockout (UVLO)
- Output Over-Voltage Protection (OVP)
- Short-Circuit Detection
- Thermal Shutdown (TSD) Protection
- Low Profile 6-lead 2.0 x 2.0 x 0.55 mm UMLP Package
- This Device is Pb–Free, Halogen Free/BFR Free and is RoHS Compliant

#### **Applications**

- Cellular Mobile Handsets
- Mobile Internet Devices
- Portable Media Players
- PDA, DSC, MP3 Players



# ON Semiconductor®

www.onsemi.com



UDFN6 2 x 2, 0.65P CASE 517DS

#### MARKING DIAGRAM

&Z&2&K 341

&Z = Assembly Plant Code &2 = 2-Digit Date Code

&K = Lot Code

341 = Specific Device Code

#### ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

**Table 1. ORDERING INFORMATION** 

Part Number	Temperature Range	Package	Packing Method <sup>†</sup>		
FAN5341UMPX	−40°C to 85°C	6-lead, 2.0 x 2.0 mm UMLP	3000 / Tape & Reel		

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# **TYPICAL APPLICATION DIAGRAM**

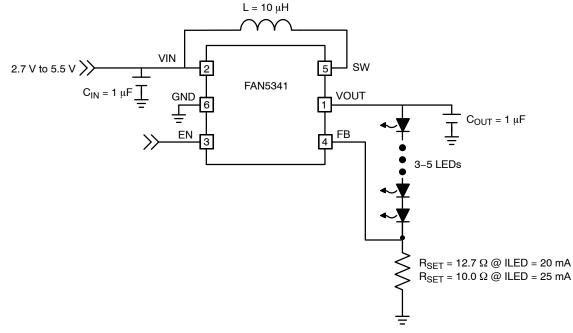


Figure 1. Typical Application

#### **BLOCK DIAGRAM**

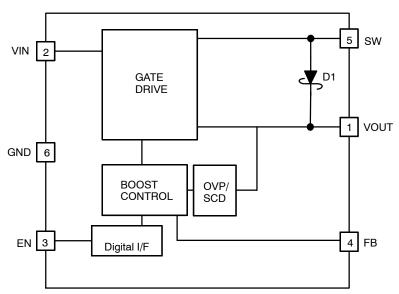


Figure 2. Functional Block Diagram

# **PIN CONFIGURATION**

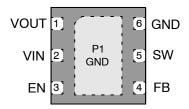


Figure 3. UMLP6 Package (Top View)

**Table 2. PIN DEFINITIONS** 

Pin #	Name	Description
		Boost Output Voltage. Output of the boost regulator. Connect the LEDs to this pin. Connect $C_{OUT}$ (Output Capacitor) to GND.
2	VIN	Input Voltage. Connect to power source and decouple with C <sub>IN</sub> to GND.
3	EN	Enable Brightness Control. Program dimming levels by driving pin with digital pulses.
4	FB	Voltage Feedback. The boost regulator regulates this pin to 0.253 V to control the LED string current. Tie this pin to a current setting resistor ( $R_{\text{SET}}$ ) between GND and the cathode of the LED string.
5 SW Switching node. Tie inductor L1 from VIN		Switching node. Tie inductor L1 from VIN to SW pin.
6	GND	Ground. Tie directly to a GND plane.

**Table 3. ABSOLUTE MAXIMUM RATINGS** 

Symbol	Parameter			Max.	Units
V <sub>IN</sub>	VIN Pin	-0.3	6.0	V	
V <sub>FB</sub> , V <sub>EN</sub>	FB, EN Pins	-0.3	V <sub>IN</sub> + 0.3	V	
V <sub>SW</sub>	SW Pin			22.0	V
V <sub>OUT</sub>	VOUT Pin			22.0	V
ESD	Electrostatic Discharge Protection	Human Body Model per JESD22-A114	3.3		kV
	Level	Charged Device Model per JESD22-C101	2.0		
T <sub>J</sub>	Junction Temperature		-40	+150	°C
T <sub>STG</sub>	Storage Temperature			+150	°C
T <sub>L</sub>	Lead Soldering Temperature, 10 Seconds			+260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

**Table 4. RECOMMENDED OPERATING CONDITIONS** 

Symbol	Parameter		Min.	Max.	Units
V <sub>IN</sub>	V <sub>IN</sub> Supply Voltage		2.7	5.5	V
V <sub>OUT</sub>	VOUT Voltage (Note 1)		6.2	17.5	V
I <sub>OUT</sub>	VOUT Load Current	500 mW Maximum Output Power	5	25	mA
T <sub>A</sub>	Ambient Temperature		-40	+85	°C
TJ	Junction Temperature		-40	+125	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

<sup>1.</sup> Application should guarantee that minimum and maximum duty-cycle should fall between 20-85% to meet the specified range.

#### **Table 5. THERMAL PROPERTIES**

Symbol	Parameter	Typical	Units	
$\theta_{JA}$	Junction-to-Ambient Thermal Resistance, UMLP6 Package	70	°C/W	

NOTE: Junction-to-ambient thermal resistance is a function of application and board layout. This data is measured with four-layer 2s2p boards in accordance to JEDEC standard JESD51. Special attention must be paid not to exceed junction temperature T<sub>J(max)</sub> at a given ambient temperature T<sub>A</sub>.

# **Table 6. ELECTRICAL SPECIFICATIONS**

 $(V_{IN} = 2.7 \text{ V to } 5.5 \text{ V} \text{ and } T_A = -40 \text{C to } +85 ^{\circ}\text{C} \text{ unless otherwise noted.}$  Typical values are at  $T_A = 25 ^{\circ}\text{C}$  and  $V_{IN} = 3.6 \text{ V.})$ 

Symbol	Parameter	Conditions	Min	Тур	Max	Units
POWER SUPP	LIES	•				
I <sub>SD</sub>	Shutdown Supply Current	EN = GND, V <sub>IN</sub> = 3.6 V		0.30	0.75	μΑ
V <sub>UVLO</sub>	Under-Voltage Lockout Threshold	V <sub>IN</sub> Rising	2.10	2.35	2.60	V
		V <sub>IN</sub> Falling	1.90	2.15	2.40	
V <sub>UVHYST</sub>	Under-Voltage Lockout Hysteresis			250		mV
N: ENABLE P	PIN	•		•		
V <sub>IH</sub>	HIGH-Level Input Voltage		1.2			V
V <sub>IL</sub>	LOW-Level Input Voltage				0.4	V
R <sub>EN</sub>	EN Pull-Down Resistance		200	300	400	kΩ
T <sub>LO</sub>	EN Low Time for Dimming	V <sub>IN</sub> = 3.6 V; See Figure 14	0.5		300	μs
T <sub>HI</sub>	Time Delay Between Steps	V <sub>IN</sub> = 3.6 V; See Figure 14	0.5			μs
T <sub>SD</sub>	EN Low, Shutdown Pulse Width	V <sub>IN</sub> = 3.6 V; from Falling Edge of EN	1			ms
EEDBACK AN	ND REFERENCE	•				
$V_{FB}$	Feedback Voltage	$I_{LED}$ = 20 mA from -40°C to +85°C, 2.7 V $\leq$ V $_{IN}$ $\leq$ 5.5 V	240	253	266	mV
I <sub>FB</sub>	Feedback Input Current	V <sub>FB</sub> = 253 mV		0.1	1.0	μΑ
OWER OUTP	UTS	•				
R <sub>DS(ON)_Q1</sub>	Boost Switch On-Resistance	V <sub>IN</sub> = 3.6 V, I <sub>SW</sub> = 100 mA		600		mΩ
		V <sub>IN</sub> = 2.7 V, I <sub>SW</sub> = 100 mA		650		
I <sub>SW(OFF)</sub>	SW Node Leakage (Note 2)	EN = 0, V <sub>IN</sub> = V <sub>SW</sub> = V <sub>OUT</sub> = 5.5 V, V <sub>LED</sub> = 0		0.1	2.0	μА
I <sub>LIM-PK</sub>	Boost Switch Peak Current Limit	V <sub>IN</sub> = 3.6 V		750		mA
SCILLATOR		•				
$f_{SW}$	Boost Regulator Switching Frequency		1.0	1.2	1.4	MHz
OUTPUT AND	PROTECTION	•				
V <sub>OVP</sub>	Boost Output Over-Voltage Protection		18.0	18.9	21.0	V
	OVP Hysteresis	1		0.8		
V <sub>TLSC</sub>	V <sub>OUT</sub> Short Circuit Detection Threshold	V <sub>OUT</sub> Falling		V <sub>IN</sub> – 1.4		V
V <sub>THSC</sub>	V <sub>OUT</sub> Short Circuit Detection Threshold	V <sub>OUT</sub> Rising		V <sub>IN</sub> – 1.2		V
D <sub>MAX</sub>	Maximum Boost Duty Cycle (Notes 3, 4)		85			%
D <sub>MIN</sub>	Minimum Boost Duty Cycle (Notes 3, 4)				20	1

# Table 6. ELECTRICAL SPECIFICATIONS (continued)

 $(V_{IN} = 2.7 \text{ V to } 5.5 \text{ V} \text{ and } T_A = -40 \text{C to } +85 ^{\circ}\text{C} \text{ unless otherwise noted.}$  Typical values are at  $T_A = 25 ^{\circ}\text{C}$  and  $V_{IN} = 3.6 \text{ V.})$ 

Symbol	Parameter	Conditions	Min	Тур	Max	Units
T <sub>TSD</sub>	Thermal Shutdown			150		°C
T <sub>HYS</sub>	Thermal Shutdown Hysteresis			35		°C

SW leakage current includes the leakage current of 2 internal switches, SW to GND and SW to VOUT.
 Not tested in production and guaranteed by design.
 Application should guarantee that minimum and maximum duty cycle should fall between 20–85% to meet the specified range.

# **ELECTRICAL SPECIFICATIONS**

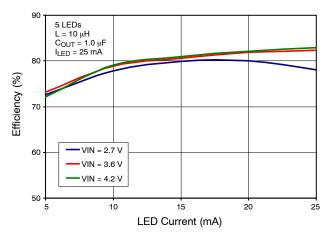


Figure 4. 5 LEDs: Efficiency vs. LED Current vs. Input Voltage

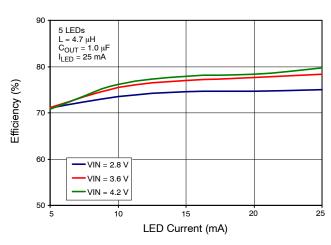


Figure 5. 5 LEDs: Efficiency vs. LED Current vs. Input Voltage

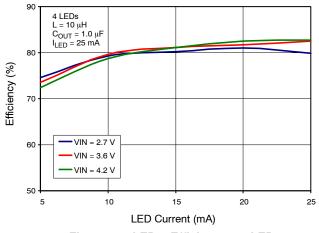


Figure 6. 4 LEDs: Efficiency vs. LED Current vs. Input Voltage

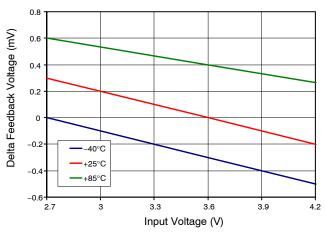


Figure 7. Delta of  $V_{FB}$  over Input Voltage and Temperature for 4 LEDs with L = 10  $\mu$ H and  $C_{OUT}$  = 1.0  $\mu$ F at  $I_{LED}$  = 25 mA

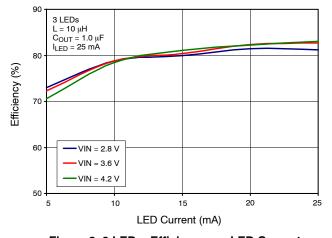


Figure 8. 3 LEDs: Efficiency vs. LED Current vs. Input Voltage

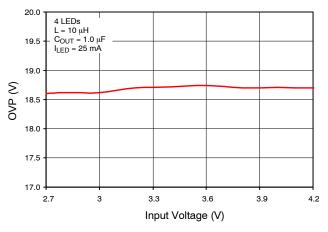


Figure 9. Over-Voltage Protection vs. Input Voltage

#### **ELECTRICAL SPECIFICATIONS** (continued)

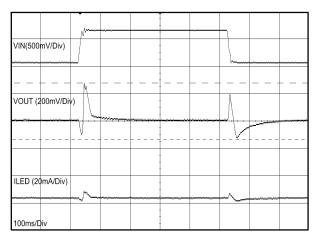


Figure 10. Line Transient Response for 4 LEDs at  $V_{IN}$  = 3.6 V  $\pm$  0.6 V with L = 10  $\mu$ H,  $C_{OUT}$  = 1.0  $\mu$ F and  $I_{LED}$  = 25 mA

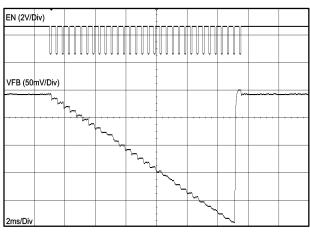


Figure 11. FAN5341 Dimming Operation at  $V_{IN}$  = 3.6 V for 4 LEDs with L = 10  $\mu$ H,  $C_{OUT}$  = 1.0  $\mu$ F and  $I_{LED}$  = 25 mA

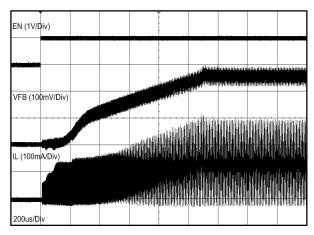


Figure 12. Startup Waveform for Switch Voltage, Inductor Current,  $V_{FB}$  and EN for 4 LEDs at  $V_{IN}$  = 3.6 V  $\pm$  0.6 V with L = 10  $\mu$ H,  $C_{OUT}$  = 1.0  $\mu$ F and  $I_{LED}$  = 25 mA

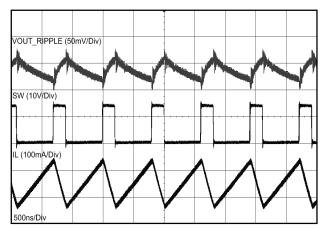


Figure 13. Steady–State Waveform for VOUT, Switch Voltage and Inductor Current for 4 LEDs at  $V_{IN}$  = 3.6 V ± 0.6 V with L = 10  $\mu$ H,  $C_{OUT}$  = 1.0  $\mu$ F and  $I_{LED}$  = 25 mA

#### CIRCUIT DESCRIPTION

#### Overview

The FAN5341 is an inductive current-mode boost serial LED driver that achieves LED current regulation by maintaining 0.253 V across the  $R_{SET}$  resistor. The current through the LED string ( $I_{LED}$ ) is therefore given by:

$$I_{LED} = \frac{0.253}{R_{SET}}$$
 (eq. 1)

The voltage  $V_{OUT}$  is determined by the sum of the forward voltages across each LED, plus the voltage across  $R_{SET}$ , which is always 253 mV.

#### **Driving Five LEDs in Series**

FAN5341 can drive five LEDs in series but, the forward voltage  $(V_F)$  of the LED MUST be less than 3.5 V such that it remains under the over-voltage specification of 18.9 V.

#### **UVLO and Soft-Start**

If EN has been low for more than 1 ms, the IC may initiate a "cold start" soft–start cycle when EN rises, provided  $V_{IN}$  is above the UVLO threshold.

#### **Digital Interface**

The FAN5341 implements a single-wire digital interface to program the LED brightness to one of thirty-two (32) levels spaced in linear steps. With this single-wire solution, the FAN5341 does not require the system processor to constantly supply a signal to it to drive the LEDs.

#### **Digital Dimming Control**

The FAN5341 starts driving the LEDs at the maximum brightness level. After startup, the control logic is ready to accept programming pulses to decrease the brightness level by the number of positive edges applied to the EN pin. Figure 14 shows the digital pulse dimming control.

# Over-Current and Short-Circuit Detection

The boost regulator employs a cycle-by-cycle peak inductor current limit of ~750 mA.

#### Over-Voltage / Open-Circuit Protection

If the LED string is an open circuit, FB remains at 0 V and the output voltage continues to increase in the absence of an over–voltage protection (OVP) circuit. The FAN5341's OVP circuit disables the boost regulator when  $V_{OUT}$  exceeds 18.9 V and continues to keep the regulator off until  $V_{OUT}$  drops below 18.1 V.

#### **Thermal Shutdown**

When the die temperature exceeds 150°C, a reset occurs and remains in effect until the die cools to 125°C, at which time, the circuit is allowed to begin the soft–start sequence.

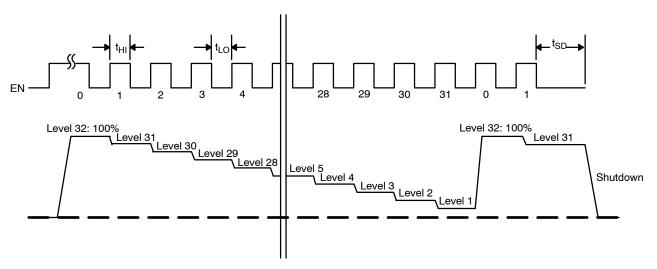


Figure 14. Digital Pulse-Dimming Control Diagram

#### **APPLICATION INFORMATION**

#### **Inductor & Output Capacitor Selection**

**Table 7. RECOMMENDED EXTERNAL COMPONENTS** 

# of LEDs	Inductor (L)	Part Number	Manufacturer	Min C <sub>OUT</sub>	Part Number	Manufacturer
3, 4, 5	10.0 μΗ	LQH43MN100K03	Murata	1.00 μF	CV105X5R105K25AT	AVX/Kyocera
		NLCV32T-100K-PFR	TDK			
		VLF3010AT-100MR49-1	TDK			
	4.7 μΗ	LQH43MN4R7K03	Murata	1.00 μF	CV105X5R105K25AT	AVX/Kyocera
		NLCV32T-4R7M-PFR	TDK			
		LPF2010T-4R7M	ABCO			

# **Component Placement and PCB Recommendations**

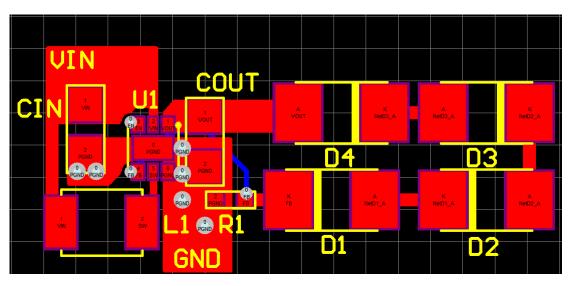


Figure 15. Recommended Component Placement

# **Input Capacitance**

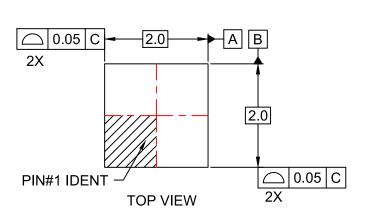
In a typical application, the input and output capacitors should be placed as close to the IC as possible; no additional capacitance is needed to ensure proper functionality. However, in a testing environment, where the FAN5341 is typically powered by a power supply with relatively long cables, an additional input capacitor (10  $\mu F)$  may be needed to ensure stable functioning. This capacitor should be placed close to where the power supply cables attach to the FAN5341 evaluation board.

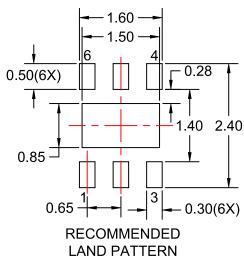
#### **PCB Recommendations**

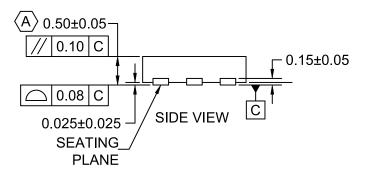
- The inductor can be connected to VIN with vias through another layer if needed.
- The feedback pin should be connected back to the IC on a sub-layer.

UDFN6 2x2, 0.65P CASE 517DS ISSUE O

**DATE 31 OCT 2016** 

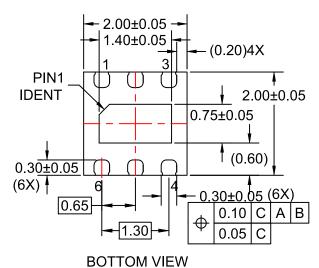






# NOTES:

- A. CONFORM TO JADEC REGISTRATIONS MO-229, VARIATION VCCC, EXCEPT WHERE NOTED.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.



DOCUMENT NUMBER:	CUMENT NUMBER: 98AON13697G Electronic versions are uncontrolled except when accessed directly from the Do Printed versions are uncontrolled except when stamped "CONTROLLED COPY"			
DESCRIPTION:	UDFN6 2x2, 0.65P		PAGE 1 OF 1	

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

ON Semiconductor and the are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and see no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and

#### **PUBLICATION ORDERING INFORMATION**

LITERATURE FULFILLMENT:
Email Requests to: orderlit@onsemi.com

ON Semiconductor Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative